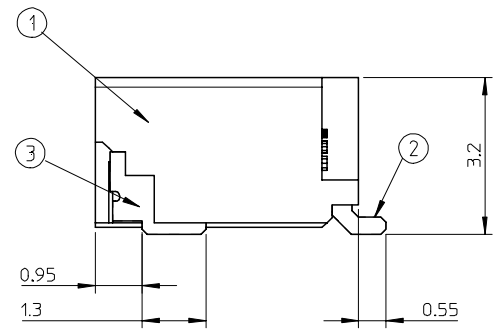
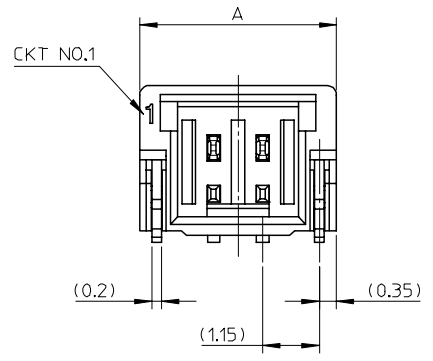


参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0、色：自然色 HEAT RESISTANCE NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	リン青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

4.0	7.0	501568-0509	5	501568-**09
3.0	6.0	501568-0409	4	
2.0	5.0	501568-0309	3	
1.0	4.0	501568-0209	2	
B	A	MATERIAL NO.	CKT	MODEL NO.

NOTES

- かん合相手 : 501330-****
MATE WITH : 501330-****
- ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
- 6~15極は、SD-501568-002を参照下さい。
REFER TO SD-501568-002 ABOUT 6-15CKT.

REVISED EC NO: J2008-0220 DRW: NABEI 2007/07/25 CHK: KYOYODA 2007/07/27 APP: NUKITA 2007/07/27	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 2-5CKT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/19			
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/19	MOLEX INCORPORATED		
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO. SD-501568-001	SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

F

E

D

C

B

A

F

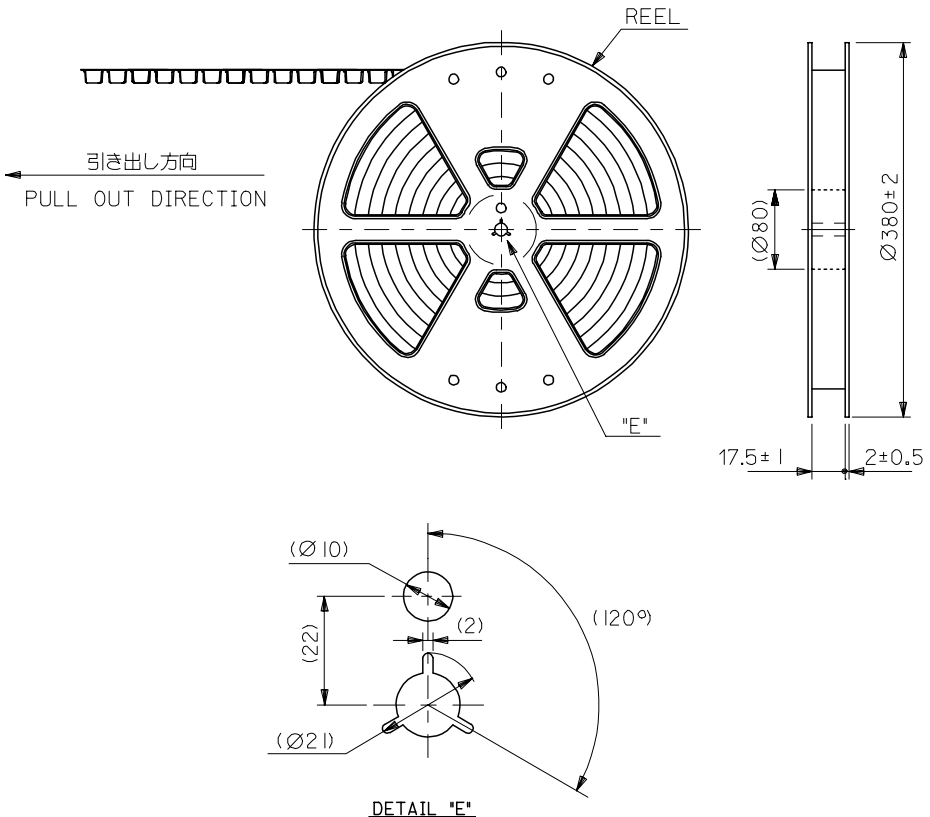
E

D

C

B

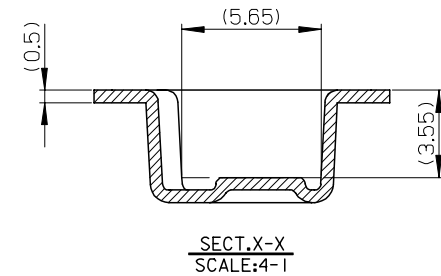
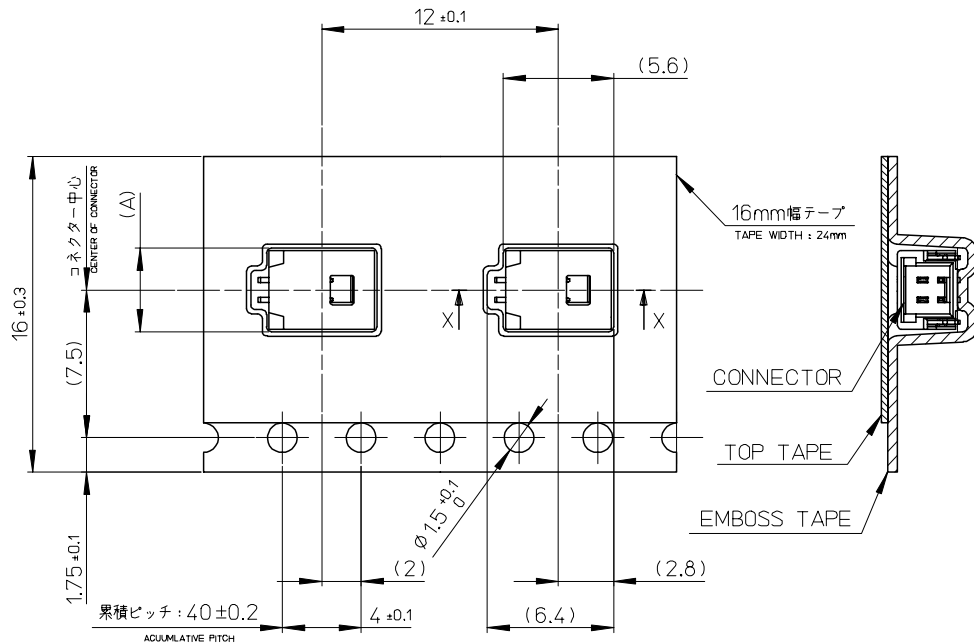
A



NOTES

- 製品詳細寸法については SD-501568-001 を参照ください。
RE DETAILED DIMENSION, SEE SD-501568-001
- 梱包数量：1700 個/リール
NUMBER OF CONNECTORS：1700PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH
- トップテープの剥離強度：0.1～1.3N(10.2～132.5gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しないこと)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.
- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE:POLYPROPYLENE
トップテープ：PET, PE, REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL : POLYSTYRENE (RECYCLE MATERIAL CONTAINED)

RELEASED EC NO: J2005-2247 DRAWN: AMI ZUMURA 2005/02/03 CHKD: MYAGI 2005/02/03 APPR: ANODA 2005/02/17 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/1/26				
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/1/26	MOLEX INCORPORATED			
	ANGULAR	±1 °	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501568-005				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



引き出し方向
PULL OUT DIRECTION

7.3	501568-0509	501568-0507	5
6.3	501568-0409	501568-0407	4
5.3	501568-0309	501568-0307	3
4.3	501568-0209	501568-0207	2
(A)	CONNECTOR	MATERIAL NO.	CKTS.

RELEASED EC NO: J2005-2247 DRWN: AMIZUMURA 2005/02/03 CHKD: MYAGI 2005/02/03 APPR: ANODA 2005/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTB PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/1/26		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/1/26	MOLEX INCORPORATED DOCUMENT NO. SD-501568-005 SHEET NO. 2 OF 2	
	ANGULAR	±3 °	MATERIAL NO.	SEE CHART		
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		